

PRINTED WIRING BOARD AND ELECTRONIC EQUIPMENT

Patent Number: JP11026907

Publication date: 1999-01-29

Inventor(s): OTAKI TORU

Applicant(s): CANON INC

Requested Patent: JP11026907

Application Number: JP19970176008 19970701

Priority Number(s):

IPC Classification: H05K1/16; H05K1/11; H05K3/46

EC Classification:

Equivalents:

Abstract

PROBLEM TO BE SOLVED: To provide a compact and light printed wiring board in which prevention of malfunction or reduction of a radiation noise can be obtained without increasing countermeasure parts.

SOLUTION: A signal pattern 2 or a ground pattern 3 are formed on a printed wiring board 1, an IC4 for outputting a digital signal is mounted on the first layer on the upper face, and an IC5 for transmitting the digital signal of the IC4 is mounted on the second layer on the lower face. The lead part of the IC4 is conducted with the signal pattern 2 of the first layer, and the lead part of the IC5 is conducted with the signal pattern 2 of the second layer. The signal pattern 2 of the first layer and the signal pattern 2 of the second layer are conducted by burying a resistive resin composition 6 in a through-hole put through the substrate 1. The ground pattern 3 of the first layer and the ground pattern 2 of the second layer are conducted by burying the resistive resin composition 6 in the through-hole made through the substrate 1.

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